

COPY

BUREAU VERITAS
Certification



Certification

Awarded to

DISCO CORPORATION

SITE DETAILS ARE SHOWN IN THE APPENDIX

Bureau Veritas Japan Co., Ltd. certify that the management system of the above organization has been audited and found to be in accordance with the requirements of the management system standards detailed below.

— STANDARDS —

ISO14001:2015, JIS Q 14001:2015

— SCOPE OF SUPPLY —

- DESIGN / DEVELOPMENT, AND MANUFACTURE, INSTALLATION / MAINTENANCE SERVICE AND SUPPLY OF SERVICE PARTS OF PRECISION PROCESSING MACHINES AND SYSTEMS, FOR CUTTING, GRINDING AND POLISHING OF SILICON WAFER AND OTHER MATERIALS.
- DESIGN / DEVELOPMENT AND MANUFACTURE OF PRECISION DIAMOND BLADES AND WHEELS, FOR CUTTING, GRINDING AND POLISHING OF SILICON WAFER AND OTHER MATERIALS.
- DESIGN, DEVELOPMENT AND MANUFACTURE OF ABRASIVE CUT-OFF WHEELS.
- SUPPLY OF PRECISION PROCESSING SERVICES.

Original Approval Date: **27 FEBRUARY 1998**

Certification Cycle Start Date: **10 AUGUST 2016**

Subject to the continued satisfactory operation of the organization's management system, this certificate is valid until: **09 AUGUST 2019**

To check this certificate validity please call (+81 45 651 4784)
Further clarifications regarding the scope of this certificate and the applicability of the management system requirements may be obtained by consulting the organization

Version: **6.0**

Approval Date: **16 JANUARY 2019**

Certificate Number: **3666516**

Bureau Veritas Japan Co., Ltd.
Certification Division
Certification Representative
Kazuhiko KAGEI



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Appendix
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Bureau Veritas Japan Co., Ltd. has issued this appendix to the Certification awarded to the above named organization.

— CERTIFICATE NUMBER —

3666516

— SITE NAME, SCOPE OF SITE and LOCATION OF SITE —

KUWABATA PLANT :

- DESIGN / DEVELOPMENT AND MANUFACTURING OF PRECISION PROCESSING MACHINES AND SYSTEMS FOR THE CUTTING, GRINDING, AND POLISHING OF SILICON WAFER AND OTHER MATERIALS.
- MANUFACTURING OF PRECISION DIAMOND BLADES AND WHEELS FOR THE CUTTING, GRINDING, AND POLISHING OF SILICON WAFER AND OTHER MATERIALS.

4010-1, GOHARA-CHO, KURE-SHI, HIROSHIMA, 737-0161, JAPAN

KURE PLANT :

- DESIGN / DEVELOPMENT, MANUFACTURING AND SALES OF PRECISION DIAMOND BLADES AND WHEELS FOR THE CUTTING, GRINDING, AND POLISHING OF SILICON WAFERS AND OTHER MATERIALS.
- DESIGN / DEVELOPMENT AND MANUFACTURING OF ABRASIVE CUT-OFF WHEELS.

1-23, HIRO BUNKA-CHO, KURE-SHI, HIROSHIMA, 737-0198, JAPAN

CHINO PLANT :

- DESIGN / DEVELOPMENT AND MANUFACTURING OF PRECISION PROCESSING MACHINES AND SYSTEMS FOR THE CUTTING, GRINDING, AND POLISHING OF SILICON WAFERS AND OTHER MATERIALS.

480, TOYOHIRA, CHINO-SHI, NAGANO, 391-0297, JAPAN

DISCO HI-TEC EUROPE GmbH :

- SALES, INSTALLATION / MAINTENANCE SERVICES AND SUPPLY OF SERVICE PARTS OF PRECISION PROCESSING MACHINES AND SYSTEMS FOR THE CUTTING, GRINDING, AND POLISHING OF SILICON WAFERS AND OTHER MATERIALS.
- SALES OF PRECISION DIAMOND BLADES AND WHEELS FOR THE CUTTING, GRINDING, AND POLISHING OF SILICON WAFERS AND OTHER MATERIALS.
- SUPPLY OF PRECISION PROCESSING SERVICES.

LIEBIGSTRASSE 8, D-85551 KIRCHHEIM B. MUENCHEN, GERMANY

Version: **6.0**

Approval Date: **16 JANUARY 2019**

Bureau Veritas Japan Co., Ltd.
Certification Division
Certification Representative
Kazuhiko KAGEI

